Product End-of-Life Disassembly Instructions

Product Category: Servers

Marketing Name / Model [List multiple models if applicable.]
Integrity BL860C Server Blade

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm Server unit is configurable and may contain some of the following assemblies: AD217-60001 PCA, Tahiti System AD217-60003 PCA, Tahiti SAS Disk Bkpl AD217-60004 PCA, Tahiti Front Panel AD270AX Itanium2 Dual Core 1.6Ghz 18MB 400/533MH AD271AX Itanium2 Dual Core 1.4Ghz 12MB 400MHz AD272AX CPU Module, HP Itanium 1p/1c 1.6MHz 6MB AB563AX 1GB DDR2 Memory [2x512MB] AB564AX 2GB DDR2 Memory [2x1GB] AB565AX 4GB DDR2 Memory [2x2GB] AB566AX 8GB DDR2 Memory [2x4GB] 314581-003 HP Integrity TPM Embedded Security Chip (AB404A) 403619-B21 HP Dual Port 4Gbps FC Mezzanine Card (Q-Logic) 431643-B21 HP Direct Adaptor Mezzanine Card 409377-B21 HP HPC 4x DDR IB Mezzanine HCA with the Voltaire GridStack software 438670-B21 HPC 4x DDR IB Mezzanine HCA with the Cisco software	22 (maximum)

	410533-B21 HP 4x DDR IB Mezzanine HCA Option Kit 447883-B21 HP 4P GigE Mezzanine Card (Ethernet)) 375859-B21 36 GB, 10K RPM SAS HotPlug Disk 375861-B21 72 GB, 10K RPM SAS HotPlug Disk 431958-B21 146 GB, 10K RPM SAS HotPlug Disk 431933-B21 36 GB, 15K RPM SAS HotPlug Disk 431935-B21 72 GB, 15K RPM SAS HotPlug Disk AB564BX 2GB DDR2 Memory [2x1GB] AB565BX 4GB DDR2 Memory [2x2GB] AB566BX 8GB DDR2 Memory [2x4GB] AD394AX Single Core 1.6GHz/12MB FSB533 (9110N processor) AD395AX Dual Core 1.42GHz/12MB FSB533 (9120N processor) AD396AX Dual Core 1.6GHz/18MB FSB667 (9140M processor)	
Batteries	All types including standard alkaline and lithium coin or button style batteries 1420-0356 BATTERY 3V .22A-H (SYSBD)	1 (maximum)
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	None
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	None
Cathode Ray Tubes (CRT)		None
Capacitors / condensers (Containing PCB/PCT)		None
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		None
External electrical cables and cords		None
Gas Discharge Lamps		None
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		None
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	None
Components and waste containing asbestos		None
Components, parts and materials containing refractory ceramic fibers		None
Components, parts and materials containing radioactive substances		None

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx Driver (T10, T15, T20, T25, T27, T30); Screwdrivers; Phillips (#0, #1, #2, #3); slotted (1/8, 5/32,	

3/16, 1/4, 5/16 in.); Ratcheting socket set;	
Description #2	
Description #3	
Description #4	
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. All panels and assemblies can be removed from the base server assemby by either Torx or screwdriver.
2. Once removed from base server, all PCAs can be removed from frame assembly by use of Torx or screwdriver.
3.
4.
5.
6.
7.
8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Template Revision B